



Final Product/Process Change Notification  
Document #:FPCN24765XB  
Issue Date:15 Dec 2025

<b>Title of Change:</b>	Qualification of mold compound second source GR710F at onsemi Suzhou, China for D2PAK devices.
<b>Proposed First Ship date:</b>	22 Mar 2026 or earlier if approved by customer
<b>Contact Information:</b>	Contact your local onsemi Sales Office
<b>PCN Samples Contact:</b>	Contact your local onsemi Sales Office. Sample requests are to be submitted no later than 30 days from the date of first notification, Initial PCN or Final PCN, for this change. Samples delivery timing will be subject to request date, sample quantity and special customer packing/label requirements.
<b>Additional Reliability Data:</b>	Contact your local onsemi Sales Office
<b>Type of Notification:</b>	This is a Final Product/Process Change Notification (FPCN) sent to customers. FPCNs are issued 90 days prior to implementation of the change. onsemi will consider this change accepted, unless an inquiry is made in writing within 30 days of delivery of this notice. To do so, contact <a href="mailto:PCN.Support@onsemi.com">PCN.Support@onsemi.com</a>
<b>Marking of Parts/ Traceability of Change:</b>	Keep same marking. Changed material will be identified by lot code.
<b>Change Category:</b>	Assembly Change
<b>Change Sub-Category(s):</b>	Material Change

**Sites Affected:**

onsemi Sites	External Foundry/Subcon Sites
onsemi Suzhou, China	None

**Description and Purpose:**

onsemi wishes to inform customers of its plan to qualify GR710F mold compound from supplier Hysol as a second source for selected D2PAK discrete products assembled at onsemi Suzhou, China. This change aims to enhance supply chain flexibility.

	Before Change Description	After Change Description
Mold Compound	CEL8240HF10FC	CEL8240HF10FC & GR710F
Mold Compound	EME 6600CS	EME 6600CS & GR710F

All other aspects of the impacted products (form, fit, function) will remain unchanged.

There is no product marking change because of this change.

There are no changes in product electrical specifications.



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**Reliability Data Summary:**

**QV DEVICE NAME: FDB2552-SB82178**

**PACKAGE: D2PAK**

**RMS: U86662**

Test	Specification	Condition	Interval	Results
HTRB	JESD22-A108	T <sub>j</sub> =175°C, 80% max rated V	1008hrs	0/231
HTGB	JESD22-A108	T <sub>j</sub> =175°C, 100% max rated V <sub>gss</sub>	1008hrs	0/231
HTSL	JESD22-A103	T <sub>a</sub> = 175°C	1008hrs	0/231
Preconditioning	J-STD-020 JESD-A113	MSL 1 @ 245 °C, Pre IOL, TC, uHAST, HAST for surface mount pkgs only		0/924
TC+PC	JESD22-A104	T <sub>a</sub> = -55°C to +150°C	1000cycs	0/231
HAST+PC	JESD22-A110	130°C, 85% RH, 18.8psig, bias	96hrs	0/231
UHAST+PC	JESD22-A118	130°C, 85% RH, 18.8psig, unbiased	96hrs	0/231
IOL+PC	MIL STD750, M 1037	T <sub>a</sub> =+25°C, delta T <sub>j</sub> =100°C max, Ton=Toff=3.5min	8572cycs	0/231
SD	JSTD002	T <sub>a</sub> = 245°C, 5 sec		0/45

**Electrical Characteristics Summary:**

Electrical characteristics are not impacted.

**List of Affected Parts:**

**Note:** Only the standard (off the shelf) part numbers are listed in the parts list. Any custom parts affected by this PCN are shown in the customer specific PCN addendum in the PCN email notification, or on the [PCN Customized Portal](#).

Part Number	Qualification Vehicle
FQB34P10TM	FDB2552-SB82178
FDB15N50	FDB2552-SB82178
FDB38N30U	FDB2552-SB82178
FQB4N80TM	FDB2552-SB82178
FQB5N90TM	FDB2552-SB82178
FQB9P25TM	FDB2552-SB82178
FQB12P20TM	FDB2552-SB82178